

ABSTRACT OF THE DISCLOSURE

A hole plugging method for a printed circuit board, a hole plugging device in accordance therewith and a manufacturing method in accordance therewith where a mask for selectively exposing a via hole, a through hole and a surface pattern of the printed circuit board is positioned on the board having the via hole and the through hole to electrically connect circuit patterns formed on the surface of the board and in the board and an insulating material is plugged in the via hole by abutting and pushing the material on the surface of the board. Therefore, the insulating material can be plugged smoothly without a void, the processing is simplified by plugging the insulating material just to the height of the circuit pattern in a space between the circuit patterns and accordingly, damage to the circuit pattern can be prevented.